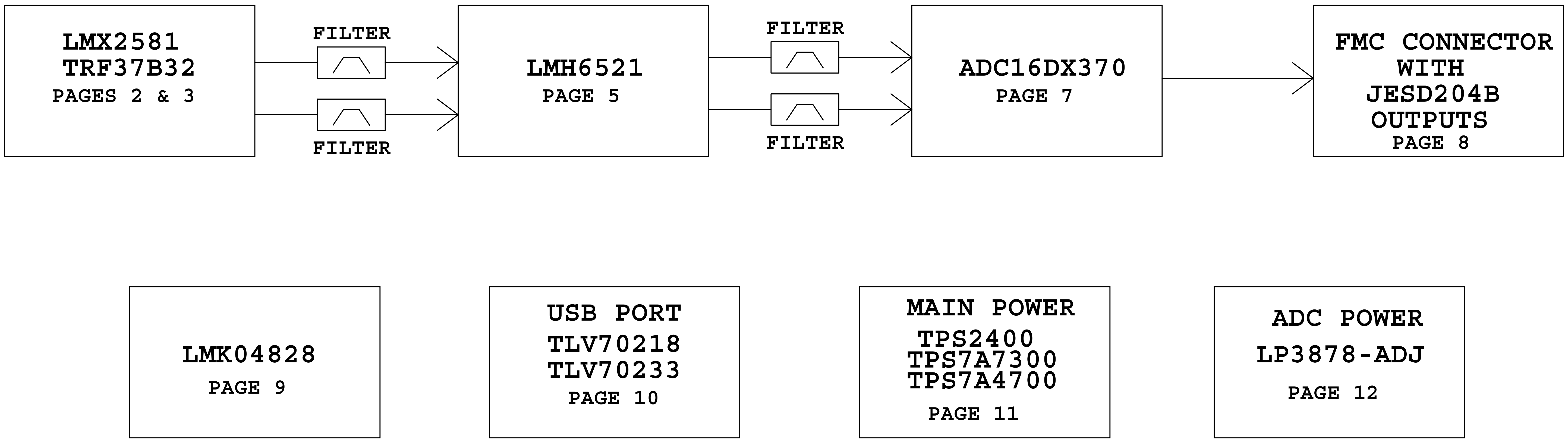


Engineer:
Josh Carnes 11/2014
Drawn By:
JV Smith 11/2014
FILE:

Title
SCH, TSW16DX370 EVM

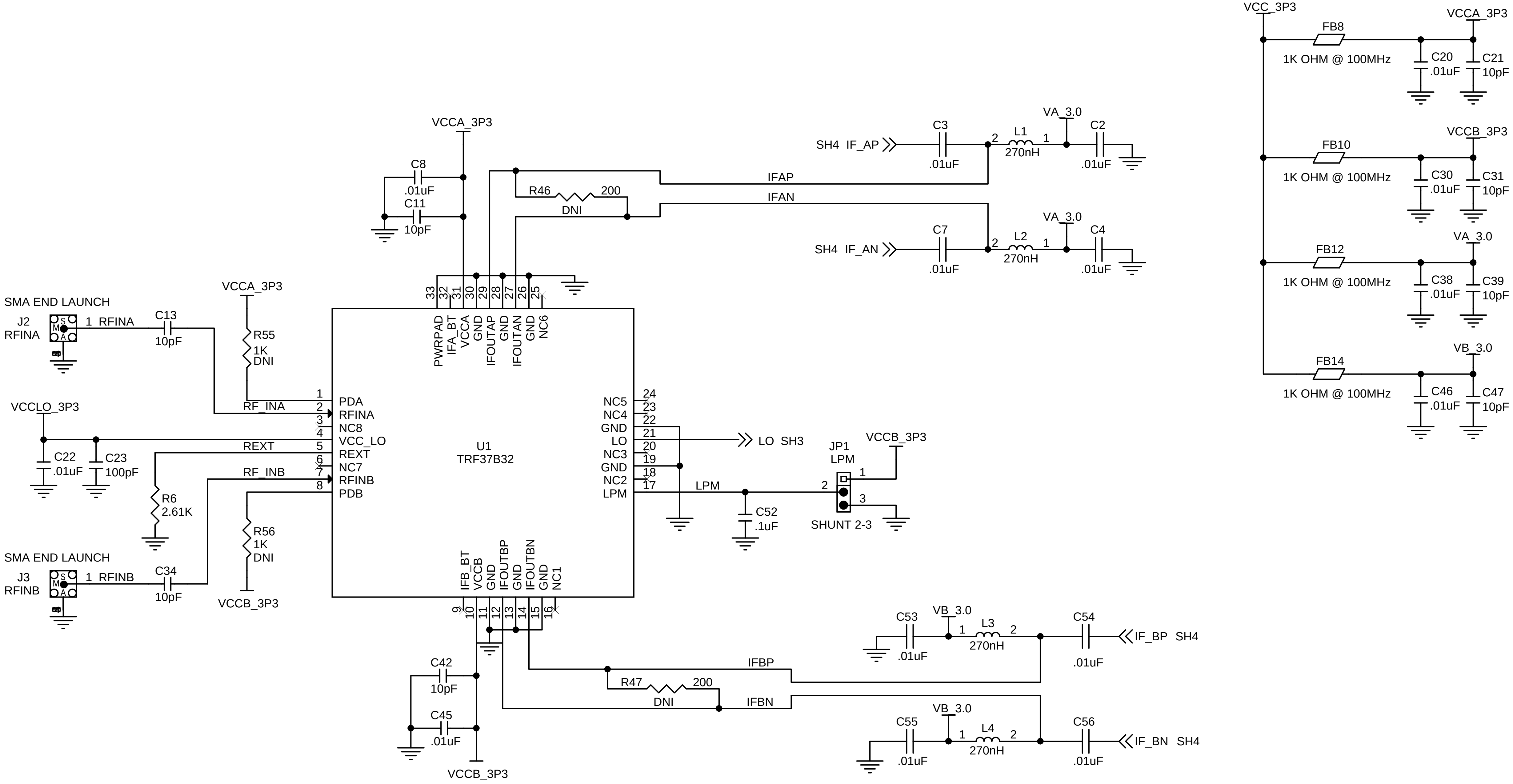
Size
B

Document Number
BLOCK DIAGRAM

Rev
B

Date: Tuesday, December 02, 2014

Sheet 1 of 12



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Size **B**	Document Number TRF3732
Rev	**B**
Date:	Tuesday, December 02, 2014
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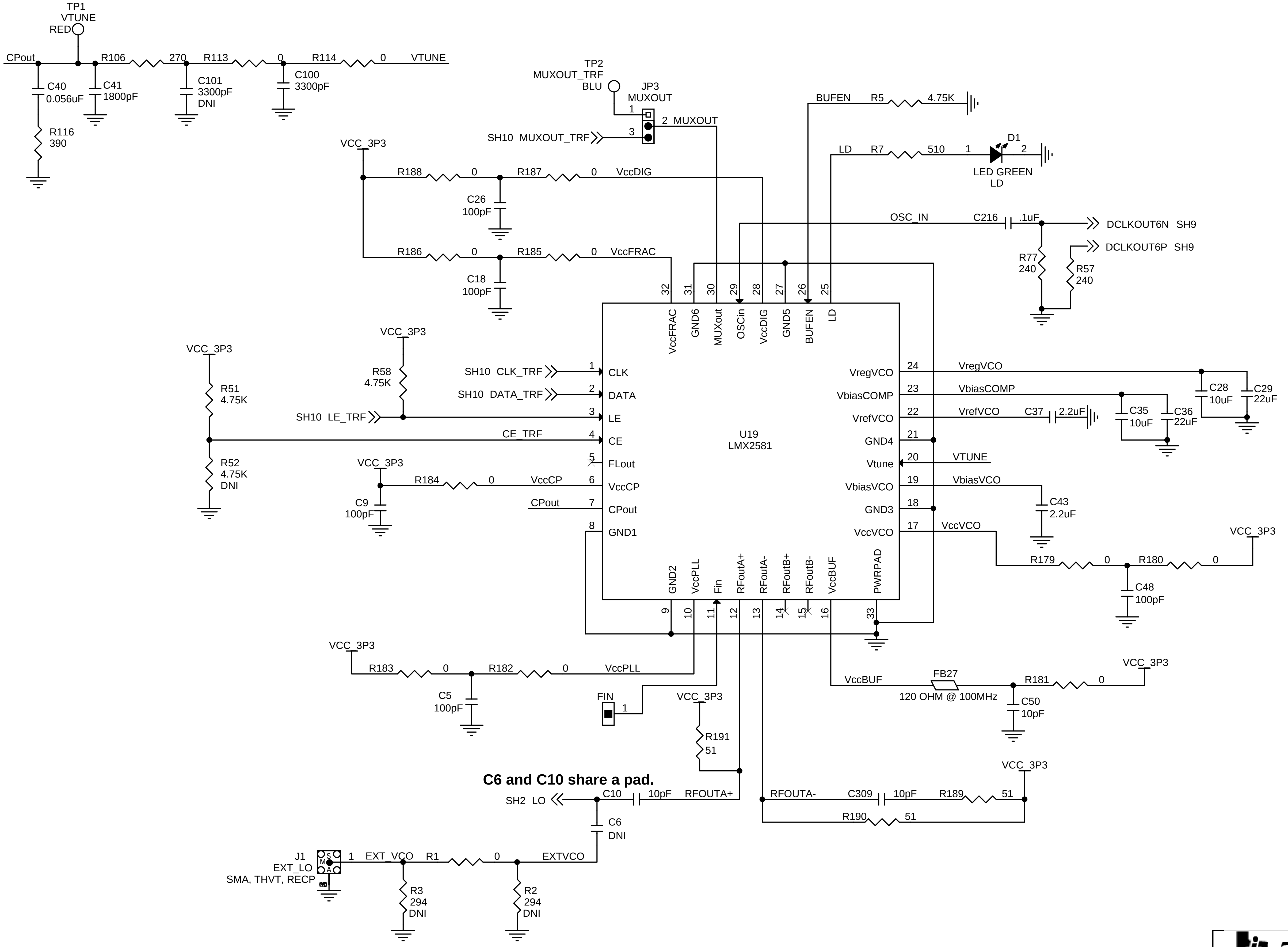

TEXAS INSTRUMENTS

Title
SCH, TSW16DX370 EVM

Size	Document Number	Rev
B	LMX2581	B

Date: Tuesday, December 02, 2014 Sheet 3 of 12

FILTER CENTER FREQUENCY AND BW
ARE HIGHLY SENSITIVE TO PCB DESIGN AND LAYOUT

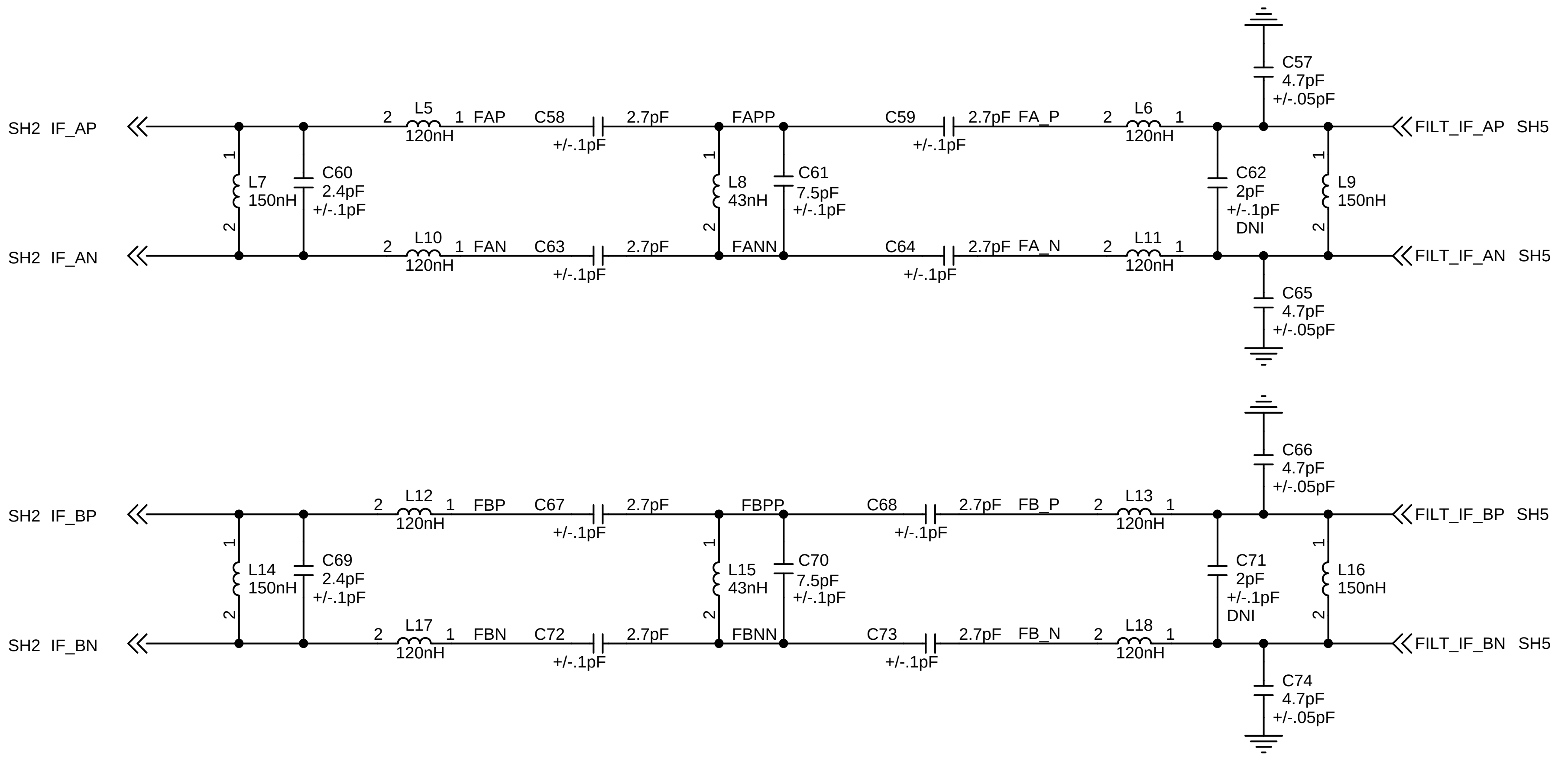

TABLE 'A'

COMPONENT	TOLERANCE
INDUCTORS	2%
COMPONENT	TOLERANCE

TEXAS INSTRUMENTS

Title
SCH, TSW16DX370 EVM

Size **B** Document Number FILTER #1 Rev **B**

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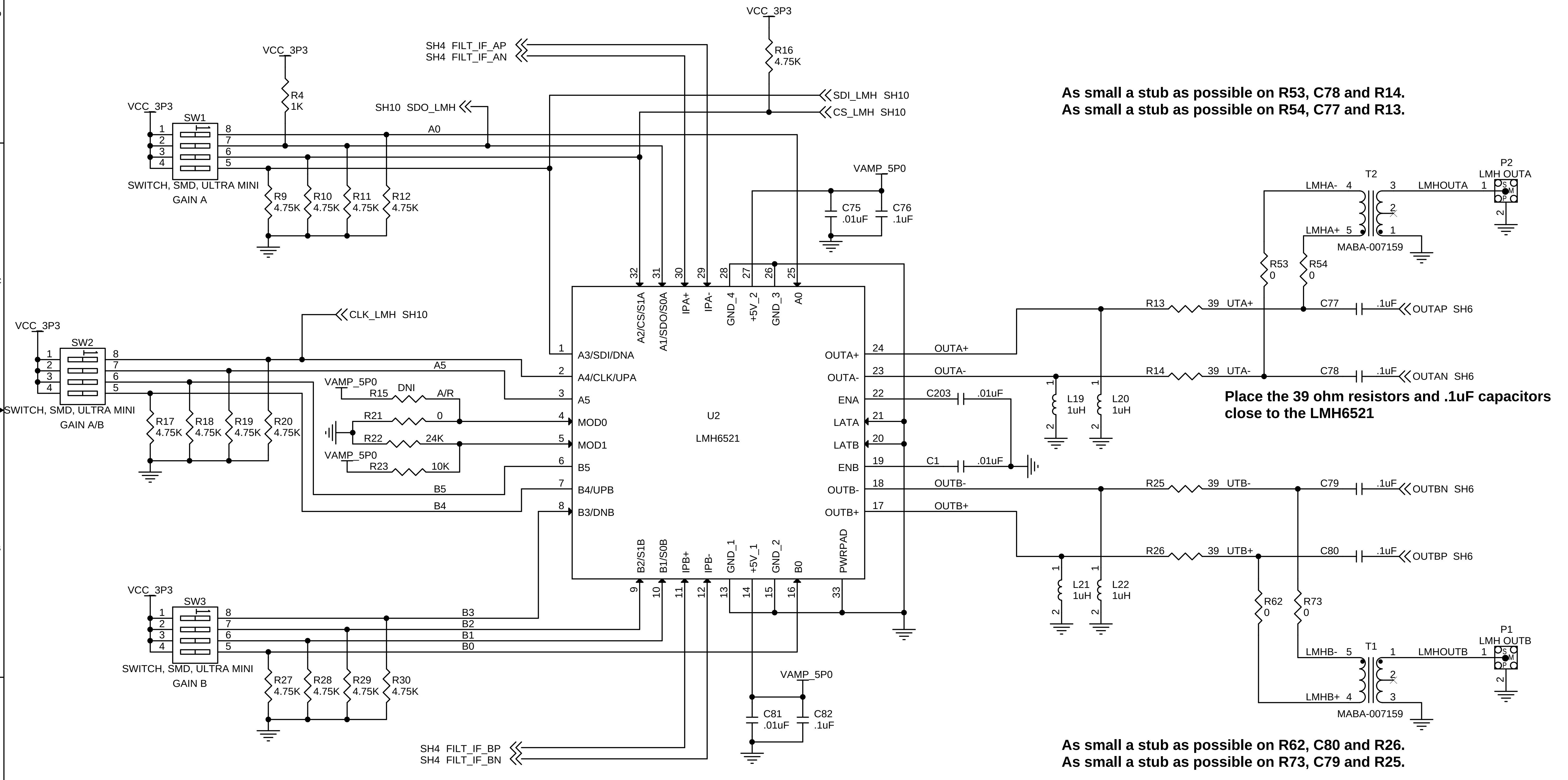

As small a stub as possible on R53, C78 and R14.
As small a stub as possible on R54, C77 and R13.

Place the 39 ohm resistors and .1uF capacitors close to the LMH6521

As small a stub as possible on R62, C80 and R26.
As small a stub as possible on R73, C79 and R25.

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SCH, TSW16DX370 EVM		
Size B	Document Number LMH6521	Rev B
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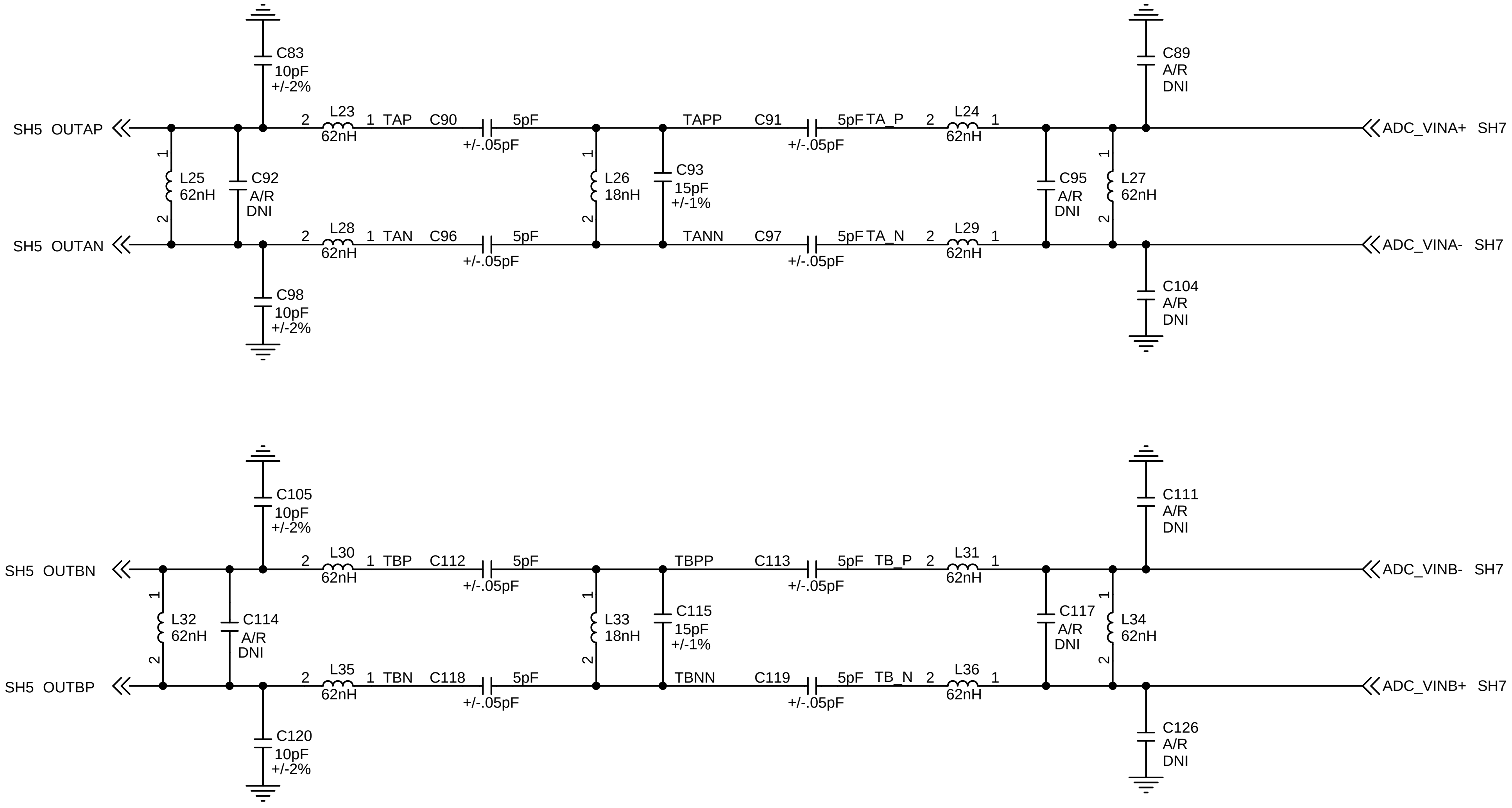
FILTER CENTER FREQUENCY AND BW
ARE HIGHLY SENSITIVE TO PCB DESIGN AND LAYOUT

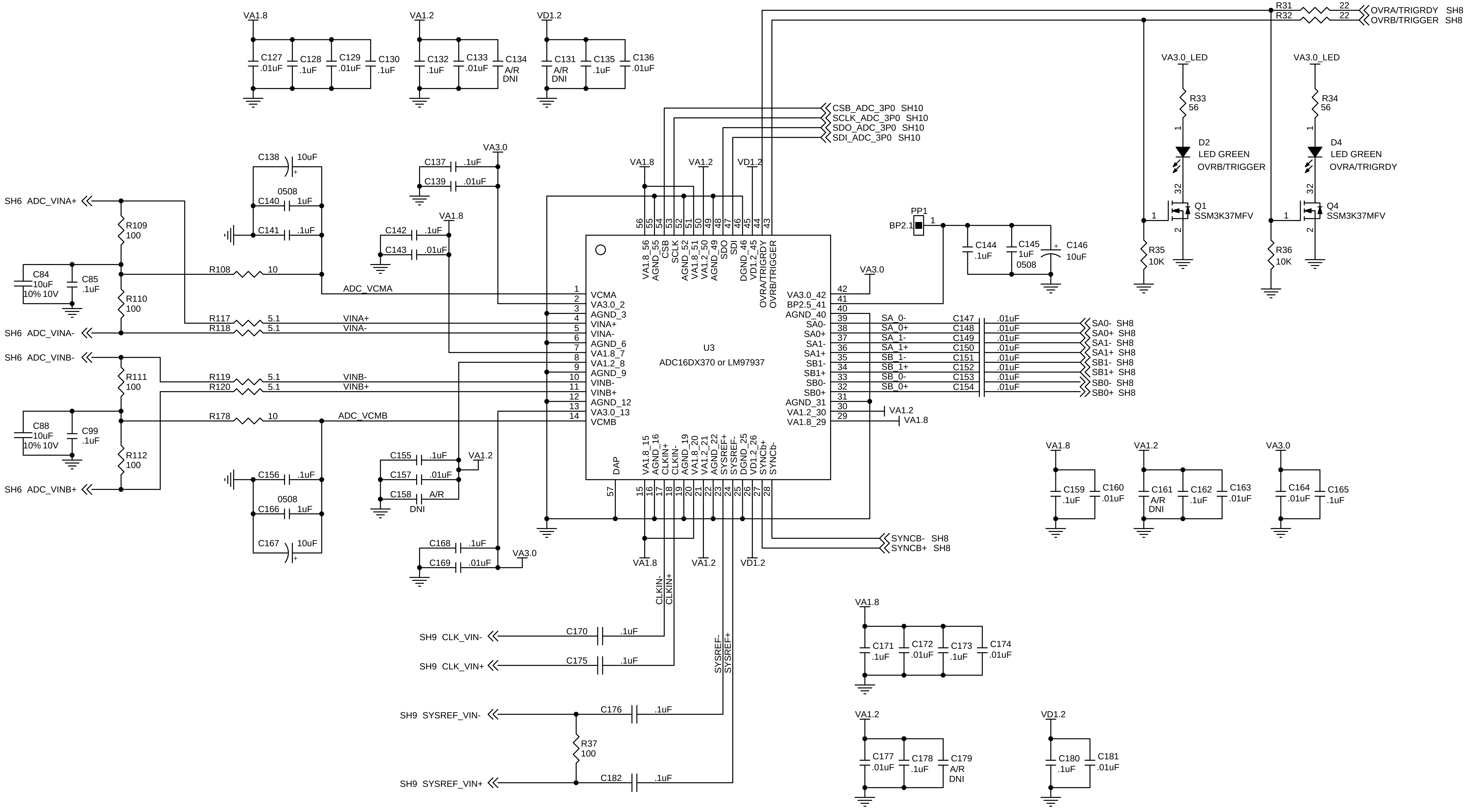


TEXAS INSTRUMENTS

Title
SCH, TSW16DX370 EVM

Size	Document Number	Rev
B	FILTER #2	B

Date: Tuesday, November 11, 2014 Sheet 6 of 12



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Title

SCH, TSW16DX370 EVM

Size B | Document Number ADC16DX370 | Rev B

Date: Tuesday, December 02, 2014 | Sheet 7 of 12

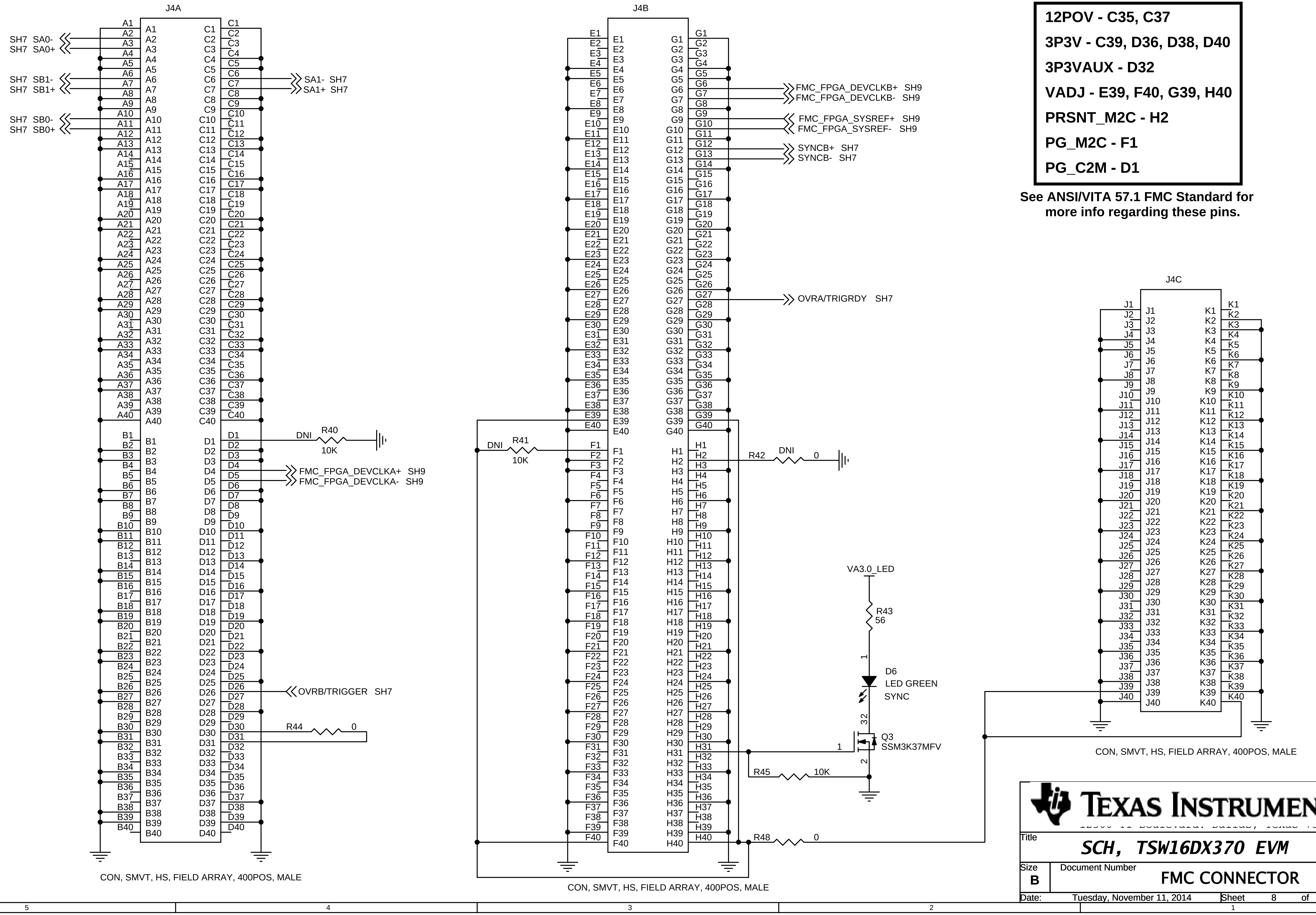

TABLE 'C'

12POV - C35, C37
3P3V - C39, D36, D38, D40
3P3VAUX - D32
VADJ - E39, F40, G39, H40
PRSNT_M2C - H2
PG_M2C - F1
PG_C2M - D1

See ANSI/VITA 57.1 FMC Standard for more info regarding these pins.

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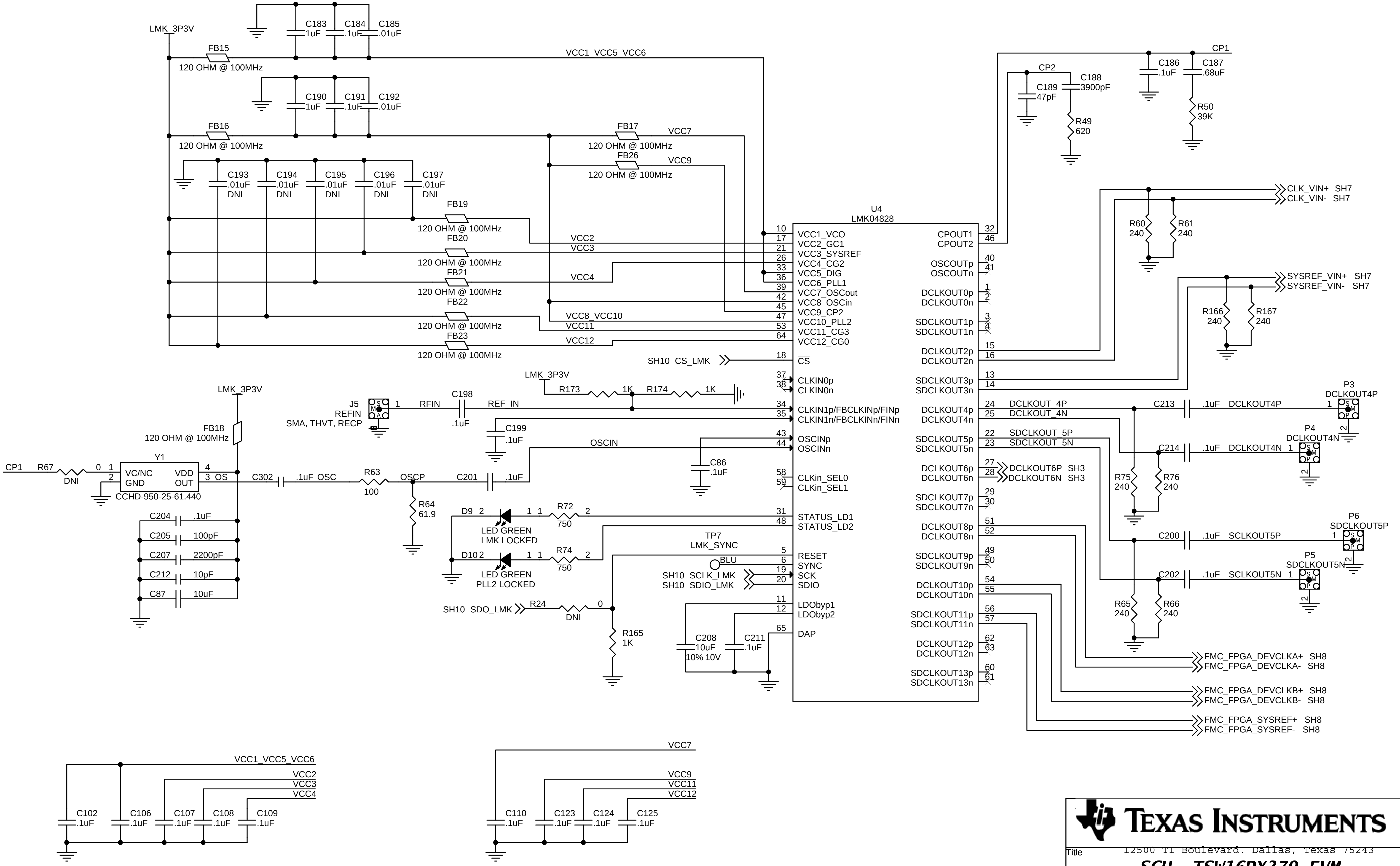
Title: *SCH, TSW16DX370 EVM*
Size: B
Document Number: FMC CONNECTOR
Rev: B
Date: Tuesday, November 11, 2014
Sheet 8 of 12



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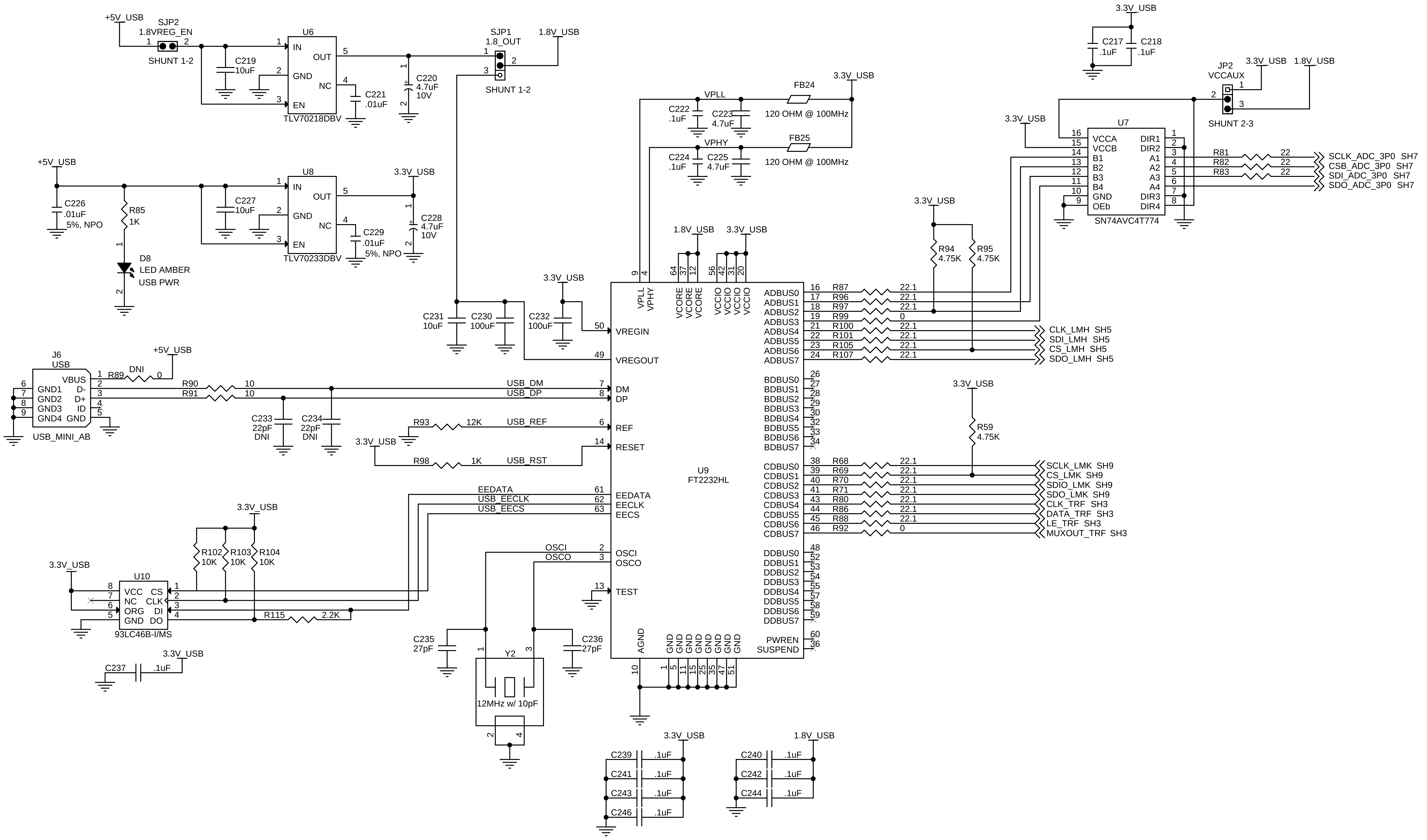
Title **SCH, TSW16DX370 EVM**

Size **B**
Document Number LMK04828
Rev **B**

Date: Tuesday, December 02, 2014 Sheet 9 of 12

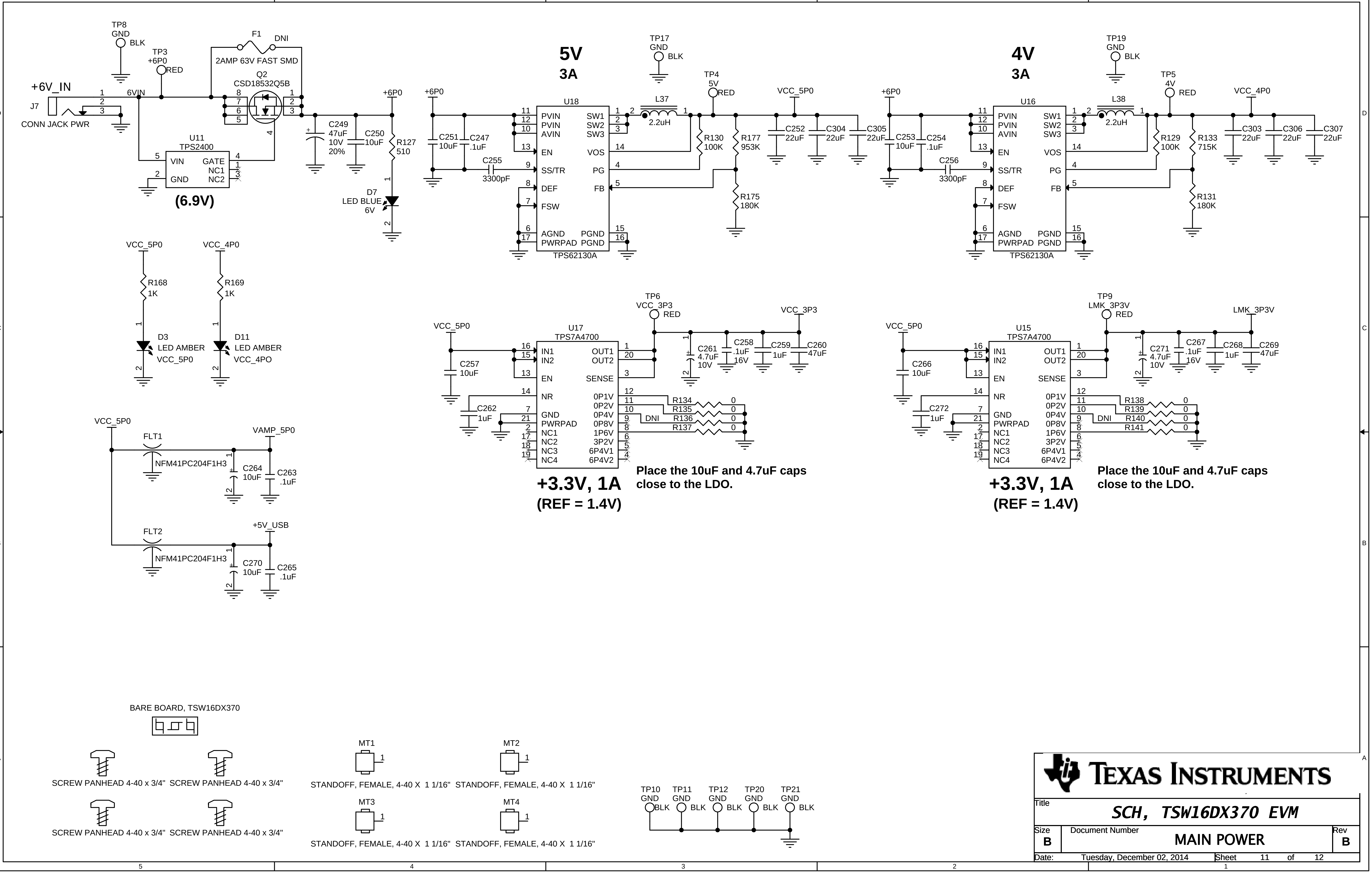


TEXAS INSTRUMENTS

Title
SCH, TSW16DX370 EVM

Size	Document Number	Rev
B	USB I/F	B

Date: Tuesday, December 02, 2014 Sheet 10 of 12

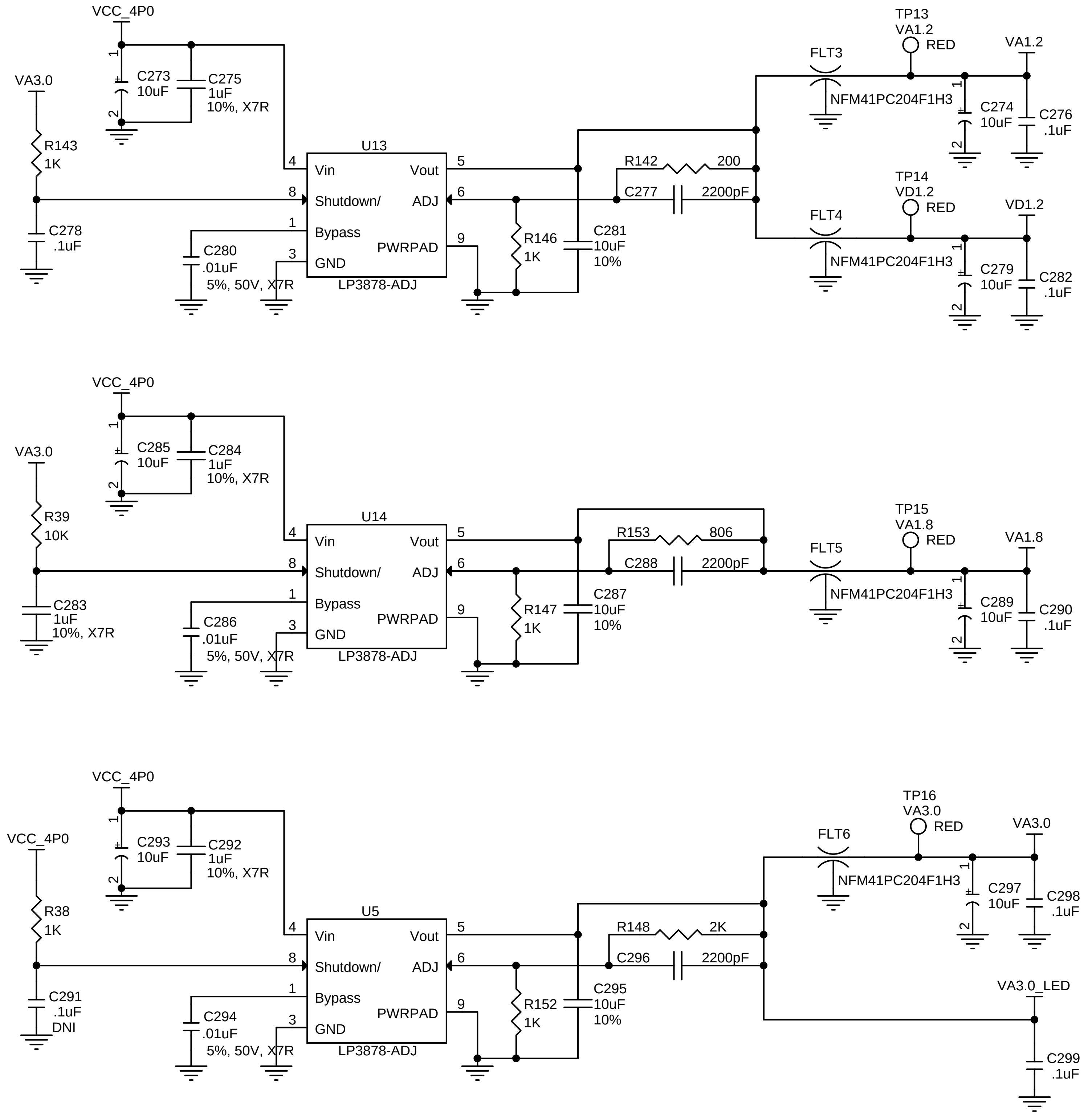


TEXAS INSTRUMENTS

Title
SCH, TSW16DX370 EVM

Size B
Document Number MAIN POWER
Rev B

Date: Tuesday, December 02, 2014
Sheet 11 of 12



TEXAS INSTRUMENTS

Title
SCH, TSW16DX370 EVM

Size B
Document Number ADC POWER
Rev B

Date: Tuesday, November 11, 2014
Sheet 12 of 12

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